

# Front-side photon detection improvement of SPAD integrated in FD-SOI CMOS Technology thanks to STI patterning

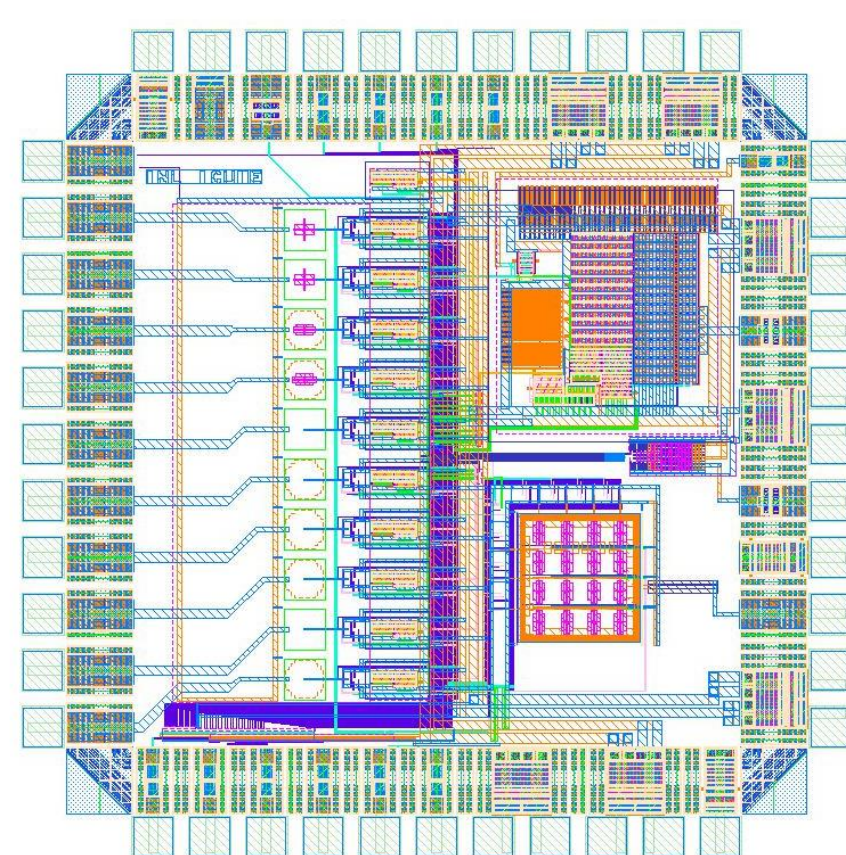
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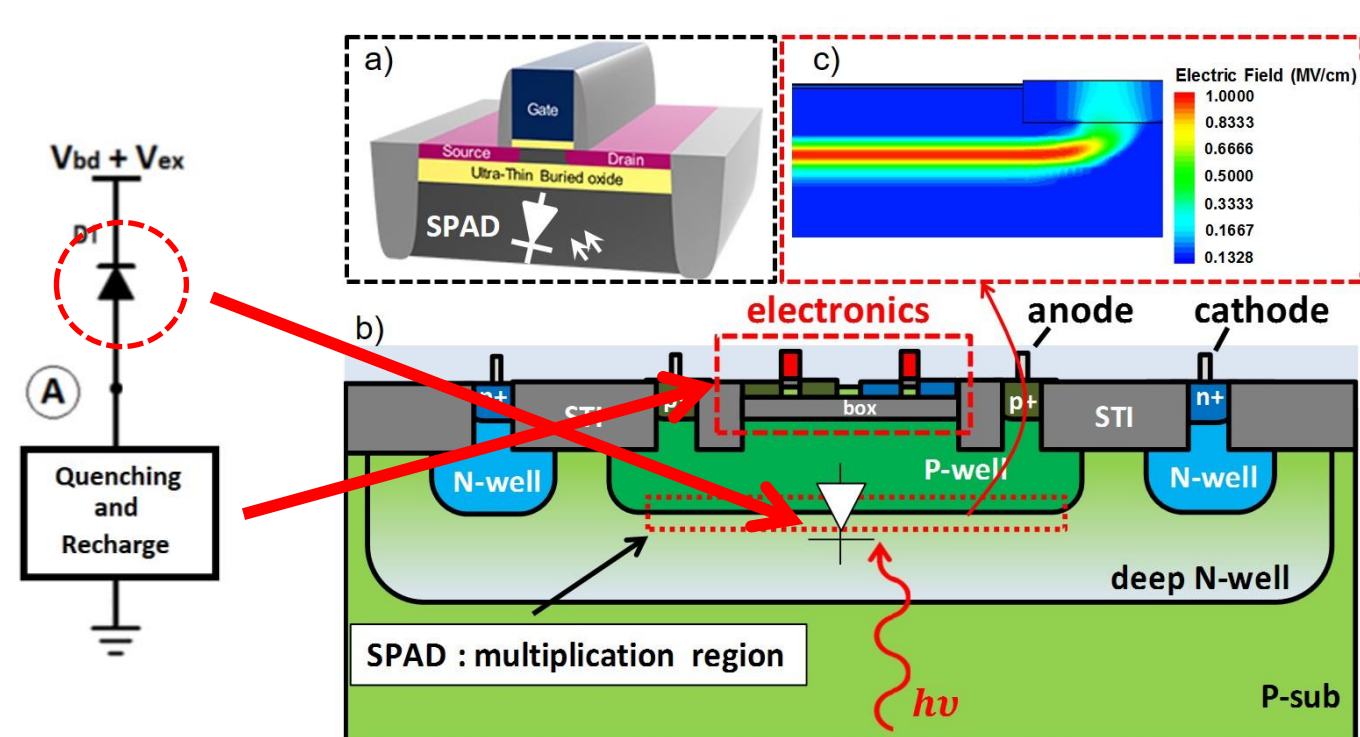
## Context

## STI patterning simulation

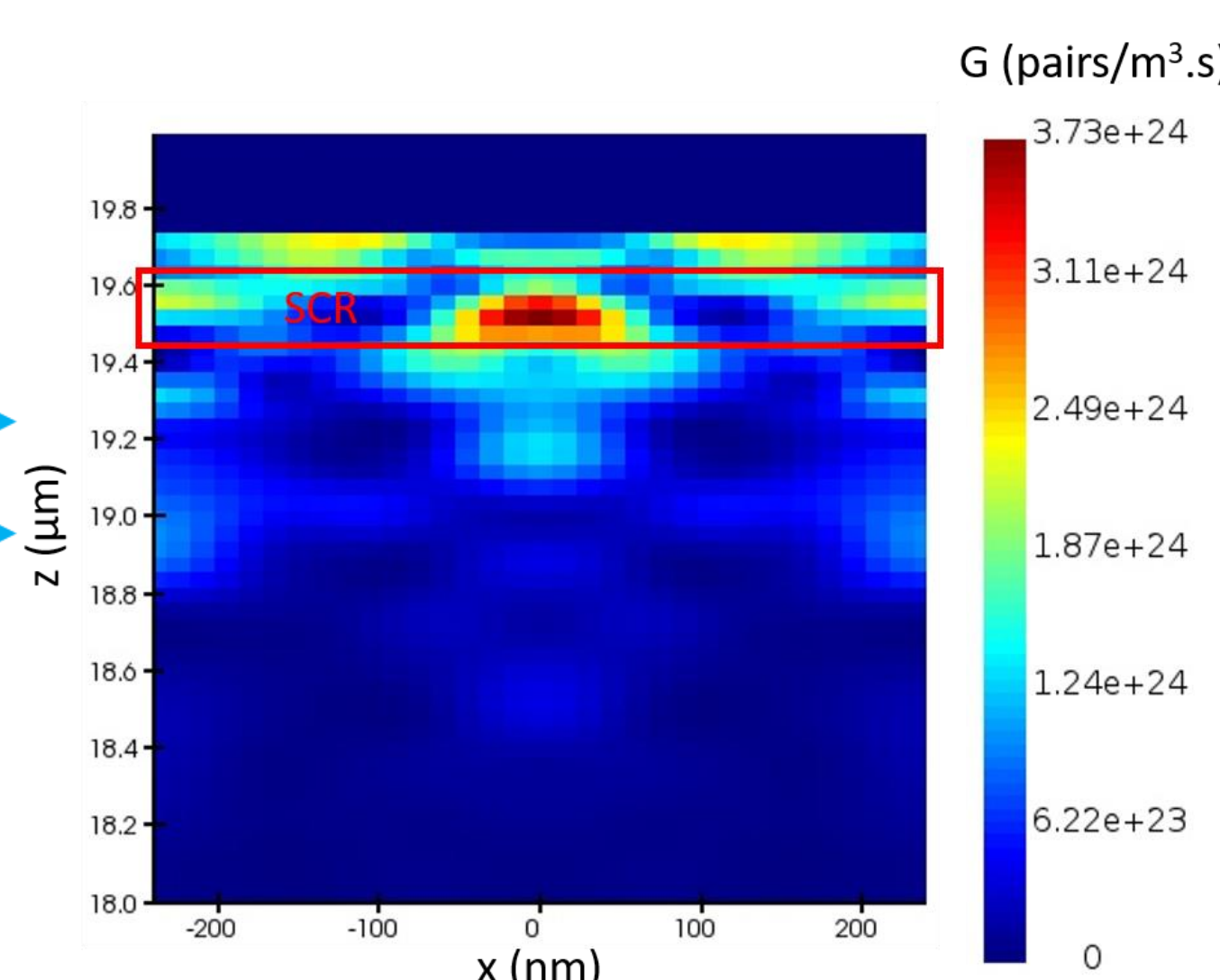
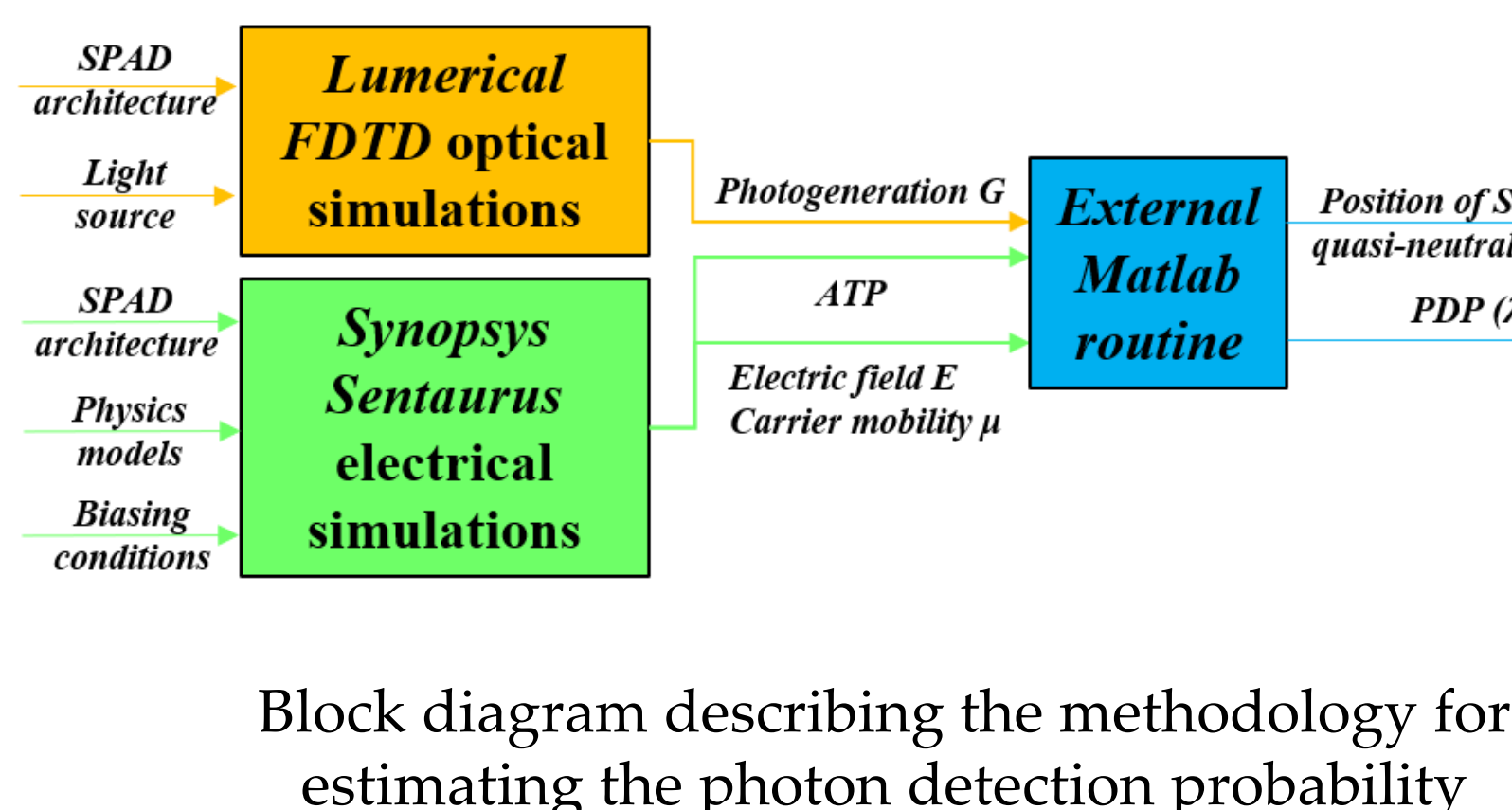
- SPAD integrated in CMOS FDSOI 28nm
- PDP improvement → Nanostructuration of STI
- Test chip designed and fabricated



Test chip layout view

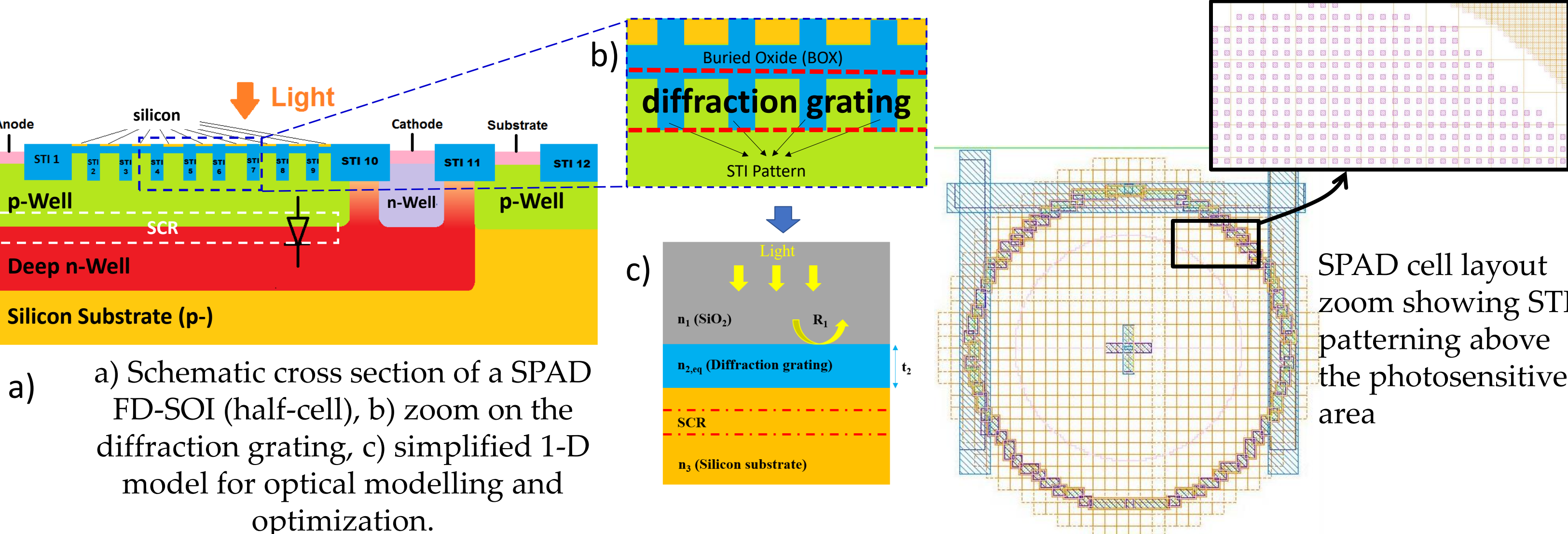


Implementation of SPAD in CMOS FD-SOI technology below the thin silicon film and the buried oxide (BOX)



Cartography of photogeneration rate on periodic pattern for FF = 15% and period = 0.48 μm

- Electro-optical simulation with Matlab post-processing
- Optimization of squared STI pattern
  - Fill Factor (FF) → Anti reflection
  - Period → Constructive interferences in space charge region
- ➔ FF = 25% and 15%, period = 480nm

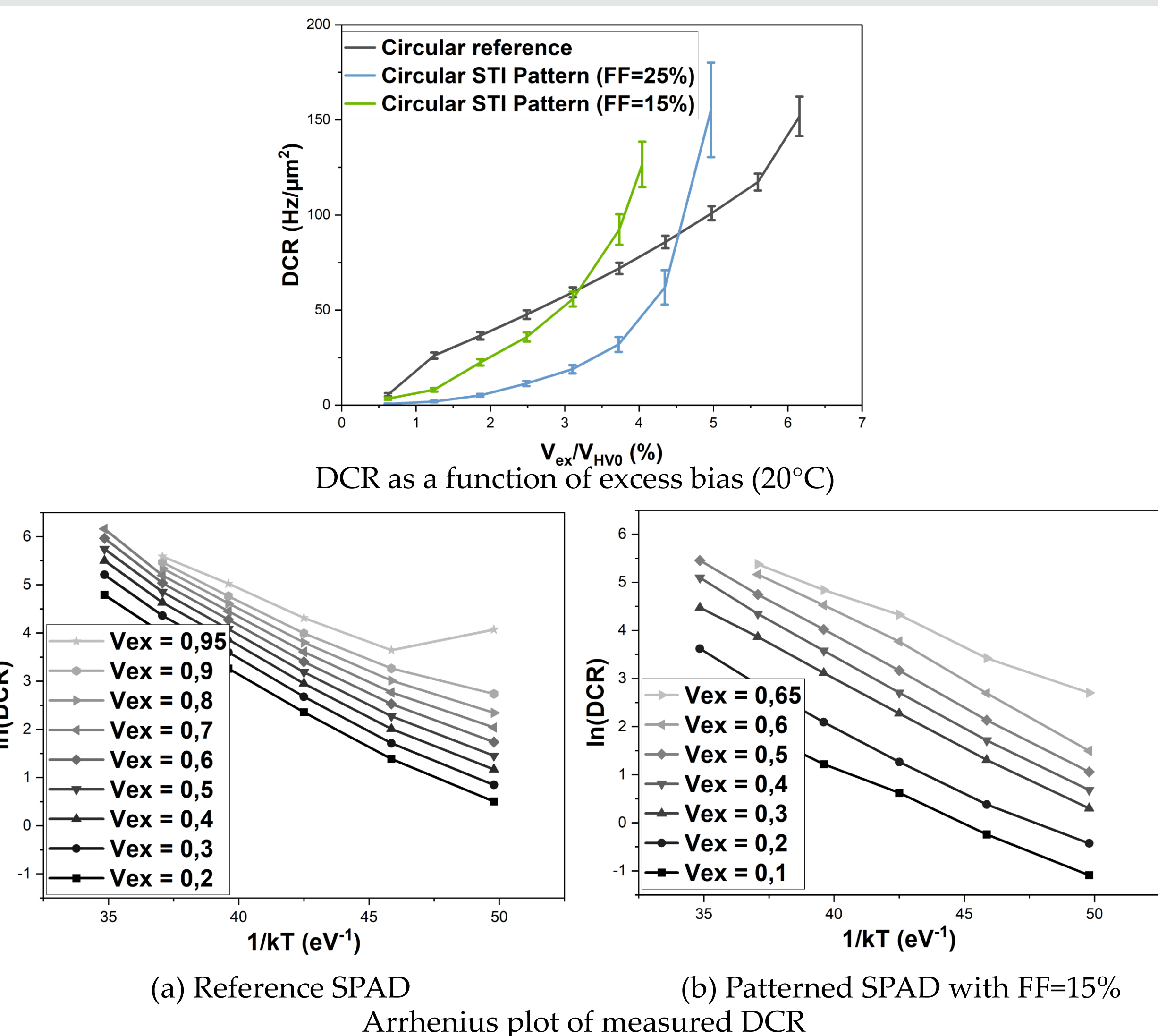


a) Schematic cross section of a SPAD FD-SOI (half-cell), b) zoom on the diffraction grating, c) simplified 1-D model for optical modelling and optimization.

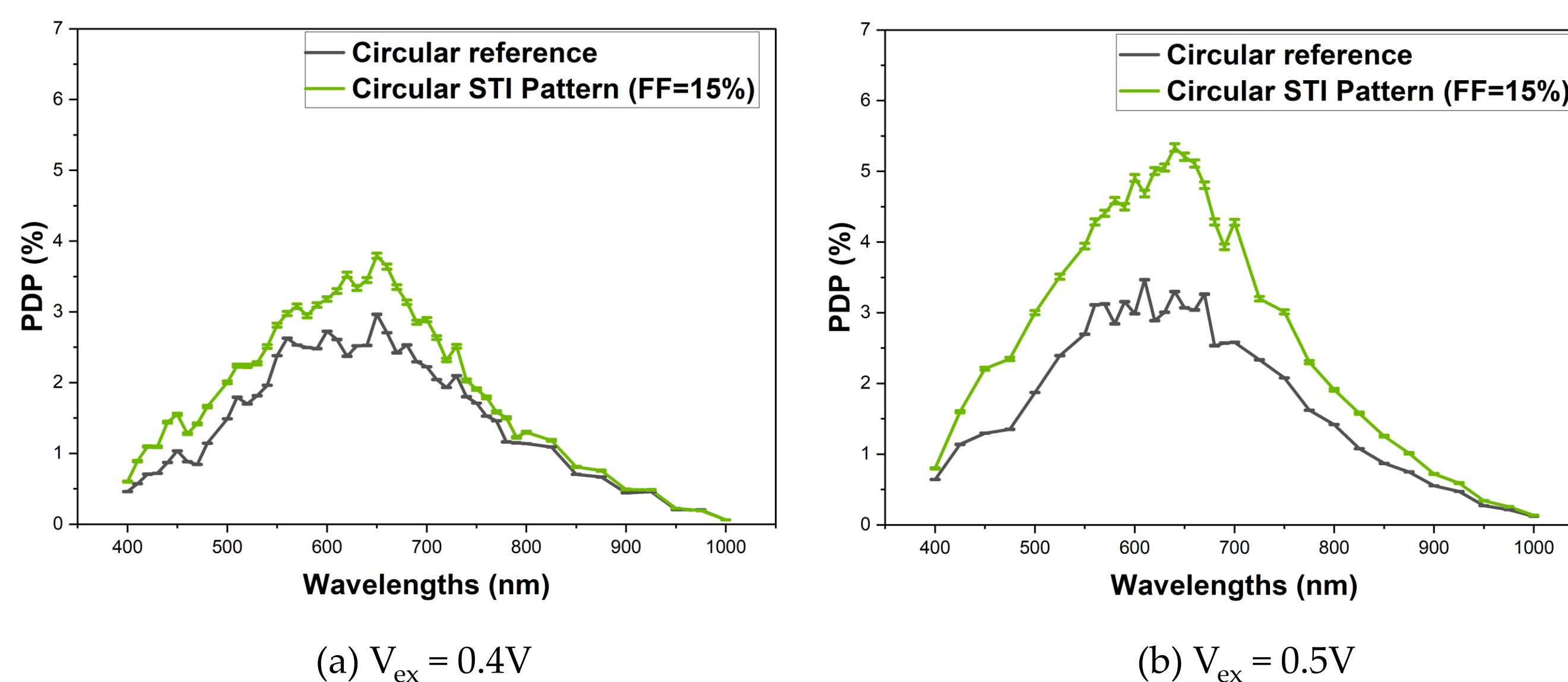
## Experimental results

### DCR measurements of patterned and reference SPAD

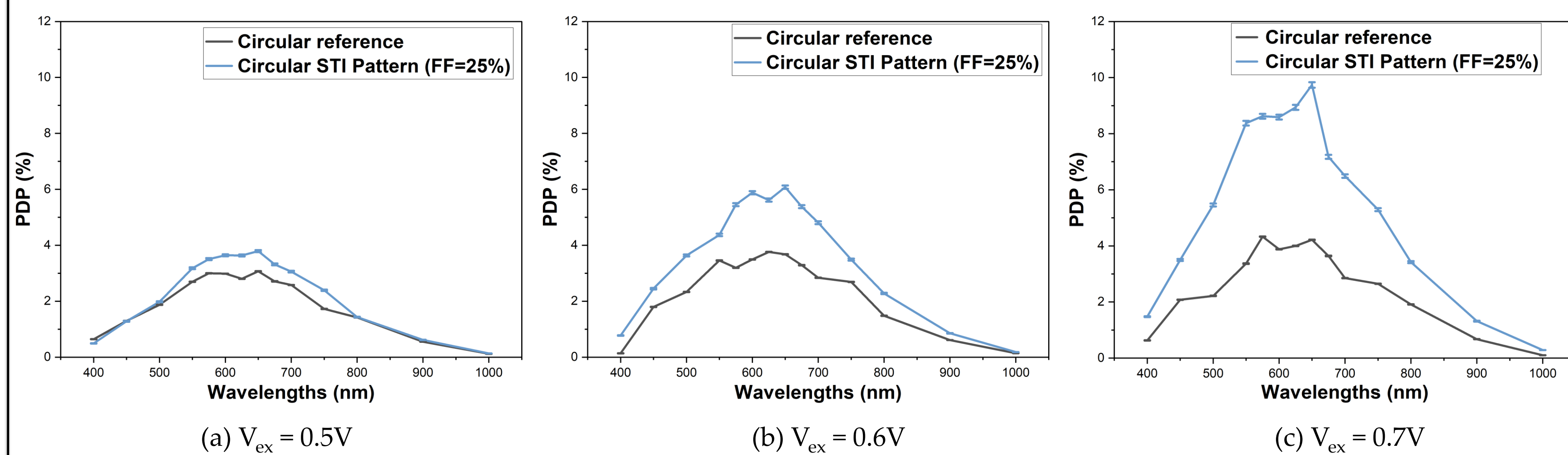
- $V_{bd} = f(T)$  : Same  $V_{bd}$  and slope ( $\approx 20\text{mV/K}$ ) for reference and patterned SPAD
- $DCR = f(T)$  :
  - $DCR_{FF=25\%} < DCR_{FF=15\%} < DCR_{ref}$  for  $V_{ex} < 4\%$
- $E_a \approx 0.3 \text{ eV}$  for both reference and patterned SPAD
- ➔ presence of both SRH and B2B-TAT mechanisms



### PDP measurements of patterned SPAD with FF = 15%



### PDP measurements of patterned SPAD with FF = 25%



### Summary of measured relative PDP gains

Fill Factor	Relative PDP gain at peak sensitivity ( $\lambda \sim 645\text{nm}$ )	Average relative PDP gain in the range [400nm - 1000nm]
FF = 15%	28% @ $V_{ex} = 0.4\text{V}$	33% @ $V_{ex} = 0.4\text{V}$
	62% @ $V_{ex} = 0.5\text{V}$	55% @ $V_{ex} = 0.5\text{V}$
FF = 25%	23% @ $V_{ex} = 0.5\text{V}$	12% @ $V_{ex} = 0.5\text{V}$
	65% @ $V_{ex} = 0.6\text{V}$	53% @ $V_{ex} = 0.6\text{V}$
	131% @ $V_{ex} = 0.7\text{V}$	116% @ $V_{ex} = 0.7\text{V}$

## References

- [1] T. Chaves de Albuquerque et al. "Integration of SPAD in 28nm FDSOI CMOS technology," ESSDERC 2018 (<http://dx.doi.org/10.1109/ESSDERC.2018.8486852>).
- [2] M. Dolatpoor Lakeh et al. "Integration of an Ultra-Fast Active Quenching Circuit with a Monolithic 3D SPAD Pixel in a 28 nm FD-SOI CMOS Technology" Sensors and Actuators: A. Physical, Volume 363, 1 December 2023, 114744 (<https://doi.org/10.1016/j.sna.2023.114744>).
- [3] D. Issartel et al. "Architecture optimization of SPAD integrated in 28 nm FD-SOI CMOS technology to reduce the DCR," Solid-State Electronics, Elsevier, Volume 191, April 2022, p. 108297 (<https://doi.org/10.1016/j.sse.2022.108297>).
- [4] S. Gao et al. "Correlations between DCR and PDP of SPAD integrated in a 28 nm FD-SOI CMOS Technology" IISW 2023, available online: <https://imagesensors.org/>.
- [5] S. Gao et al. "3D Electro-optical Simulations for Improving the Photon Detection Probability of SPAD Implemented in FD-SOI CMOS Technology" SISPAD conference, 27-29 Sept. 2021: (<https://doi.org/10.1109/SISPAD54002.2021.9592555>)

- PDP improvement thanks to STI patterning

- Up to 116% average PDP improvement with similar DCR level